Product / Package Information

Package	LFCSP
Body Size (mm)	5 X 5
Lead Count	32
Terminal Finish	NiPdAu
MS Number	

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.93E-02	86.20	862000	48.76	487600
Thermosets	Epoxy resin	Proprietary	2.04E-03	6.00	60000	3.39	33940
Thermosets	Phenol Resin	Proprietary	2.04E-03	6.00	60000	3.39	33940
Other inorganic materials	Metal Hydroxide	Proprietary	5.10E-04	1.50	15000	0.85	8485
Other inorganic materials	Carbon Black	1333-86-4	1.02E-04	0.30	3000	0.17	1697
Subtotal			3.40E-02	100.00	1000000	56.57	565661

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.34 E-02	97.50	975000	38.89	388942
Copper & its alloys	Iron	7439-89-6	5.63 E-04	2.35	23500	0.94	9375
Copper & its alloys	Zinc	7440-66-6	2.88 E-05	0.12	1200	0.05	479
Copper & its alloys	Phosphorus	7723-14-0	7.19 E-06	0.03	300	0.01	120
Subtotal			2.40 E-02	100.00	1000000	39.89	398915

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	5.79 E-04	97.3	973000	0.96	9626
Precious metals	Palladium	7440-05-3	1.31 E-05	2.2	22000	0.02	218
Precious metals	Gold	7440-57-5	2.97 E-06	0.5	5000	0.005	49
Subtotal			5.95 E-04	100.00	1000000	0.99	9893

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.28 E-04	100.0	1000000	0.21	2128

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.05 E-03	100.0	1000000	1.76	17552

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.83 E-04	80.50	805000	0.47	4710
Other organic materials	Carbocyclic Acrylates	Proprietary	3.52 E-05	10.00	100000	0.06	585
Other organic materials	Bismaleimide resin	Proprietary	1.05 E-05	3.00	30000	0.02	176
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	1.05 E-05	3.00	30000	0.02	176
Others	Additive	Proprietary	1.05 E-05	3.00	30000	0.02	176
Other organic materials	Dicumyl peroxide	80-43-3	1.76 E-06	0.50	5000	0.00	29
Subtotal			3.52 E-04	100.0	1000000	0.59	5851

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.01 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.